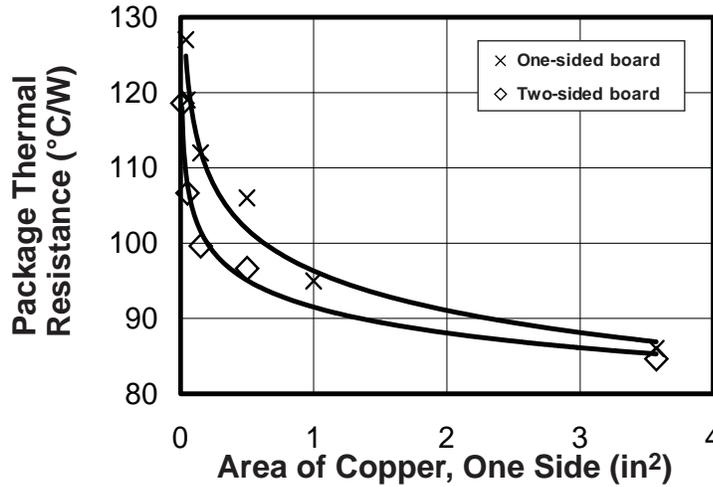


Effect of PWB Copper Area on Thermal Performance of 4-Lead SIP (Suffix SH) Package

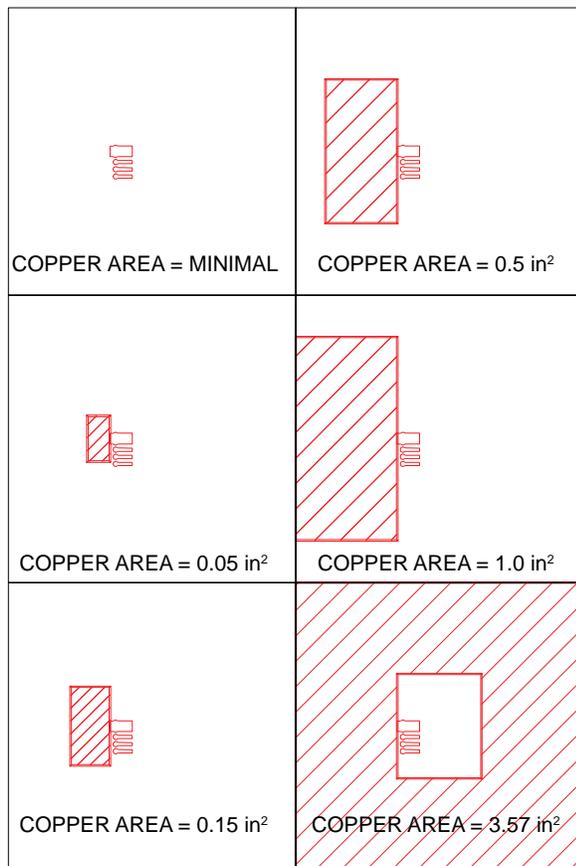
Thermal Resistance ($R_{\theta JA}$) versus Copper Area on Printed Wire Board (PWB)



- All copper is 2 oz. thickness
- Area of Copper refers to individual test locations on PWB

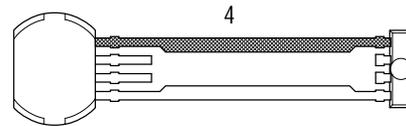
Variable Copper Area Test Board

Red hatched areas are copper on the surface of the PWB



Package Ground Pin Must Be Connected to Copper Area on Board

The SH package has one ground lead, as shown by the black hatched area. This lead should be attached to the additional copper area on the PWB.



Using a 2-Layer PWB

For the 2-layer board (copper on 2 sides), the copper area on the bottom is identical to the area on the top. Both the top and bottom layers are thermally connected through vias located next to the ground lead.

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